

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/388,826
Confirmation No. 4483
Filing Date September 1, 1999
Inventor Weimin (Michael) Li et al.
Assignee Micron Technology, Inc.
Group Art Unit 2813
Examiner E. Kielin
Attorney's Docket No. MI22-1208
Customer No. 021567
Title: Low k Interlevel Dielectric Layer Fabrication Methods

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References -See Attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the references which are listed on the attached Form PTO-1449, copies of which are attached.

No admission is made regarding whether all the submitted references are prior art.

Citation of the referenced art is respectfully requested.

Respectfully submitted,

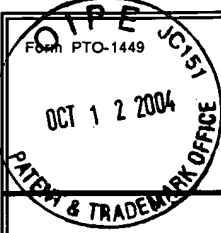
Dated: 12 Oct 2004

By: James E. Lake
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		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-1208		SERIAL NO. 09/388,826	
		LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)					
		APPLICANT Weimin Li, et al.				FILING DATE September 1, 1999	
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	6,638,875	10/2003	Han et al			
	AB	6,720,247	04/2004	Kirkpatrick et al			
	AC	6,723,631	04/2004	Noguchi et al			
	AD	6,627,535	09/2003	MacNeil et al			
	AE	2003/0077916	04/2003	Xu et al			
	AF	2003/0207594	11/2003	Catabay et al			
	AG	2004/0071878	04/2004	Schuhmcher et al			
	AH						
	AI						
	AJ						
	AK						
	AL						
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation
							Yes No
	AM						
	AN						
	AO						
	AP						
	AQ						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AR						
	AS						
	AT						
EXAMINER				DATE CONSIDERED			
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>							